Layer Stack Up Detail for: SAT0020E2.PcbDoc

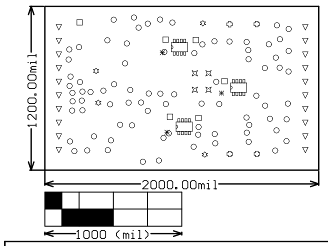
Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	
			FR-4 High Tg
GND	(.GP1)	1.4mil	
			FR-4 High Tg
VCC	(.GP2)	1.4mil	
			FR-4 High Tg
Bottom Layer	(.GBL)	1.4mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2000MIL X 1200MIL

Number of Layers : 4
MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 8 MIL
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.20mm (8MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
☐ FR-4 ☒ FR-4 High Tg ☐ OTHER ______
THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER ______
TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- ______
COPPER THICKNESS (FINISHED):
OUTER: ☒ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☐ 2.8MIL (2oz)
INNER SIGNAL: ☒ 1.4MIL (1oz) ☐ 2.8MIL (2oz) ☐ N/A
DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER ______
BOARD FINISH:
SILKSCREEN: ☒ TOP ☒ BOTTOM
SILKSCREEN COLOR: ☒ WHITE ☐ OTHER ______
SOLDER RESIST COLOR:
☐ GREEN ☐ BLUE ☒ OTHER RED
SURFACE FINISH: ☒ IMMERSION GOLD (ENIG)
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER ______
ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S ID/LOGO: ☐ RAIL ☒ METAL ☐ SILK



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	82	10mil (0.254mm)	PTH	Round
□	6	28mil (0.711mm)	PTH	Round
✧	4	38mil (0.965mm)	PTH	Round
✡	4	40mil (1.016mm)	PTH	Round
▽	20	45.276mil (1.15mm)	PTH	Round
✙	4	53mil (1.346mm)	PTH	Round
	120 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0020	REV: E2	SVN REV: Not In VersionControl
LAYER NAME = [illegible]			
PLOT NAME = Fabrication Drawing	GENERATED : 3/14/2014 5:21:24 PM		TEXAS INSTRUMENTS

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